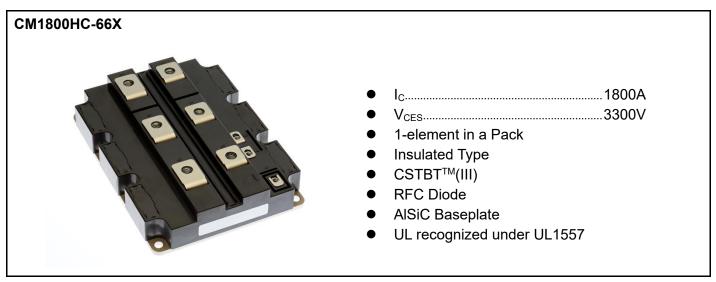


< High Voltage Insulated Gate Bipolar Transistor: HVIGBT >

CM1800HC-66X

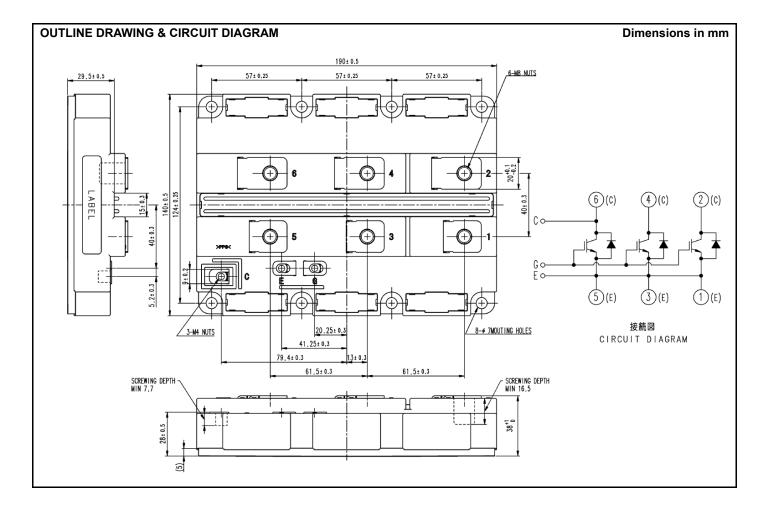
HIGH POWER SWITCHING USE INSULATED TYPE

5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules



APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers



CM1800HC-66X

HIGH POWER SWITCHING USE

INSULATED TYPE

5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

MAXIMUM RATINGS

Symbol	Item	Conditions	Ratings	Unit	
V	Collector emitter voltage	V _{GE} = 0V, T _j = -40+150°C	3300	· · ·	
V _{CES}	Collector-emitter voltage	$V_{GE} = 0V, T_j = -50^{\circ}C$	3200	V	
V_{GES}	Gate-emitter voltage	$V_{CE} = 0V, T_j = 25^{\circ}C$	±20	V	
Ic	Collector ourrent	DC, T _c = 105°C	1800	Α	
I _{CRM}	Collector current	Pulse (Note 1)	3600	Α	
I _E	Croitter current (ALL C)	DC, $T_c = 90^{\circ}C$	1800	Α	
I _{ERM}	Emitter current (Note 2)	Pulse (Note 1)	3600	Α	
P _{tot}	Maximum power dissipation (Note 3)	T _c = 25°C, IGBT part	17800	W	
V_{iso}	Isolation voltage	RMS, sinusoidal, f = 60Hz, t = 1min.	6000	V	
Ve	Partial discharge extinction voltage	RMS, sinusoidal, f = 60Hz, Q _{PD} ≤ 10pC	2600	V	
T _j	Junction temperature		−50 ~ +150	°C	
T _{jop}	Operating junction temperature		−50 ~ +150	°C	
T _{stg}	Storage temperature		− 55 ~ + 150	°C	
t _{psc}	Short circuit pulse width	$V_{CC} = 2500V, V_{CE} \le V_{CES}, V_{GE} = 15V, T_j = 150^{\circ}C$	10	μs	

ELECTRICAL CHARACTERISTICS

Cumbal	Itom	Conditions		Limits			Unit
Symbol	Item	Conditions	-		Тур	Max	Ullit
			$T_j = 25^{\circ}C$	_	_	6.0	
I _{CES}	Collector cutoff current	$V_{CE} = V_{CES}, V_{GE} = 0V$	T _j = 125°C	_	6.0	_	mA
			T _j = 150°C	_	36.0	_	
$V_{GE(th)}$	Gate-emitter threshold voltage	$V_{CE} = 10V, I_{C} = 180mA, T_{j} = 25^{\circ}C$		6.5	7.0	7.5	V
I _{GES}	Gate leakage current	$V_{GE} = V_{GES}$, $V_{CE} = 0V$, $T_j = 25$ °C		-0.5		0.5	μA
C _{ies}	Input capacitance	V _{CE} = 10V, V _{GE} = 0V, f = 100kHz		_	208	_	nF
C _{oes}	Output capacitance	, ,			14.0	_	
C_{res}	Reverse transfer capacitance	$T_j = 25^{\circ}C$			1.9		
Q_G	Total gate charge	V_{CC} = 1800V, I_{C} = 1800A, V_{GE} = ±	15V	_	13.5	_	μC
		1 = 10004 a	T _j = 25°C		2.00	_	
V_{CEsat}	Collector-emitter saturation voltage	I _C = 1800A (Note 4) V _{GE} = 15V	T _j = 125°C	_	2.50	_	V
		V _{GE} - 15V	T _j = 150°C	_	2.60	3.10	
t _{d(on)}	Turn-on delay time		T _j = 150°C	_	_	0.90	μs
t _r	Turn-on rise time	V _{CC} = 1800V	T _j = 150°C	_	_	0.50	μs
	Turn-on switching energy (Note 7)	I _C = 1800A	T _j = 25°C	_	2.95	_	J
E _{on(10%)}		$V_{GE} = \pm 15V$	T _j = 125°C	_	3.25	_	
		$R_{G(on)} = 1.5\Omega$	T _j = 150°C	_	3.40	_	
	Turn-on switching energy (Note 5)	L _S = 100nH Inductive load	T _j = 25°C	_	3.00	_	J
Eon			T _j = 125°C	_	3.40	_	
			T _j = 150°C	_	3.55	_	
			T _j = 25°C	_	2.90	_	
$t_{d(off)}$	Turn-off delay time		T _j = 125°C	_	3.20	_	μs
	•		T _j = 150°C	_	3.20	4.25	
	Turn-off fall time	V _{CC} = 1800V	T _j = 25°C	_	0.40	_	
t _f		I _C = 1800A	T _j = 125°C	_	0.45	_	μs
		$V_{GE} = \pm 15V$	T _j = 150°C	_	0.50	1.00	1.00
		$R_{G(off)} = 12\Omega$	T _j = 25°C	_	2.30	_	
E _{off(10%)}	Turn-off switching energy (Note 7)	L _S = 100nH	T _j = 125°C		3.05	_	J
		Inductive load	T _j = 150°C		3.10		<u> </u>
			T _j = 25°C		2.45		
E _{off}	Turn-off switching energy (Note 5)		T _j = 125°C		3.10	_	J
			T _j = 150°C	_	3.35	_	

CM1800HC-66X

HIGH POWER SWITCHING USE

INSULATED TYPE

5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

ELECTRICAL CHARACTERISTICS

Symbol	Item		Conditions		Limits			Unit
Symbol	item				Min	Тур	Max	Offic
V_{EC}	Emitter-collector voltage (Note 2)		1 10001	T _j = 25°C		2.20	_	
		I _E = 1800A (Note 4)	T _j = 125°C	_	2.40	_	V	
			$V_{GE} = 0V$	T _j = 150°C	1	2.50	3.00	
				T _j = 25°C	_	0.95	_	
t _{rr}	Reverse recovery time	(Note 2)		T _j = 125°C	1	1.10	_	μs
				T _j = 150°C	ı	1.15	_	
				T _j = 25°C	ı	ı	_	
Irr	Reverse recovery current	(Note 2)		T _j = 125°C	1	2350	_	Α
			T _j = 150°C	1	2500	_		
			V _{CC} = 1800V	T _j = 25°C	ı	1600	_	
Q _{rr(10%)}	Reverse recovery charge	(Note 2,6)	I _E = 1800A	T _j = 125°C	1	2400	_	μC
			V _{GE} = ±15V	T _j = 150°C		2500	_	
			$R_{G(on)} = 1.5\Omega$	T _j = 25°C	ı	1800	_	
Q_{rr}	Reverse recovery charge	(Note 2,5)	L _S = 100nH	T _j = 125°C	ı	2600	_	μC
		Inductive load	T _j = 150°C		2700	_		
				T _j = 25°C	ı	1.70	_	
E _{rec(10%)}	Reverse recovery energy	(Note 2,7)		T _i = 125°C	_	2.45	_	J
				T _i = 150°C	_	2.80	_	
				T _j = 25°C	_	1.85	_	
E _{rec}	Reverse recovery energy	(Note 2,5)		T _j = 125°C		2.60	_	J
				T _j = 150°C	_	2.95	_	

THERMAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Linit
Symbol			Min	Тур	Max	Unit
$R_{th(j-c)Q}$	The war of maniators an	Junction to Case, IGBT part	_	-	7.0	K/kW
$R_{th(j-c)D}$	Thermal resistance	Junction to Case, FWDi part	_	-	11.0	K/kW
R _{th(c-s)}	Contact thermal resistance	Case to heat sink $\lambda_{grease} = 1 \text{W/m} \cdot \text{k}, \ D_{(c-s)} = 80 \mu \text{m}$	_	5.0		K/kW

MECHANICAL CHARACTERISTICS

Symbol	Item	O and distance	Limits			1.1
		Conditions		Тур	Max	Unit
M _t		M8 : Main terminals screw	7.0	1	19.0	N⋅m
Ms	Mounting torque	M6 : Mounting screw	3.0	-	6.0	N⋅m
Mt		M4 : Auxiliary terminals screw (Note 8)	1.0	1	3.0	N⋅m
M	Mass		1	1.2	-	kg
CTI	Comparative tracking index		600	1	-	_
da	Clearance		19.5	-	_	mm
d _s	Creepage distance		32.0	1	-	mm
L _{P CE}	Parasitic stray inductance		_	8.0		nΗ
R _{CC'+EE'}	Internal lead resistance	T _C = 25°C	_	0.09		mΩ

Note1. Pulse width and repetition rate should be such that junction temperature (T_j) does not exceed T_{jopmax} rating.

 $Note 2. \hspace{0.5cm} \textbf{The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWD_i)}. \\$

Note3. Junction temperature (T_j) should not exceed T_{jmax} rating (150°C).

Note4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

Note5. Definition of all items is according to IEC 60747, unless otherwise specified.

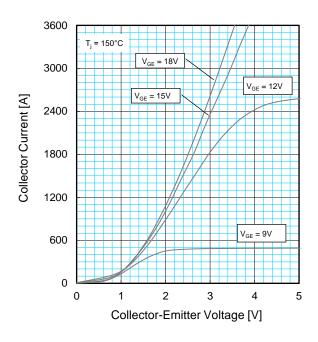
Note6. The integration range of reverse recovery charge is from I_E = 0A to 10% I_E .

Note7. The integration range of switching energies is from $10\%V_{CE}$ to $10\%I_{C}(10\%I_{E})$.

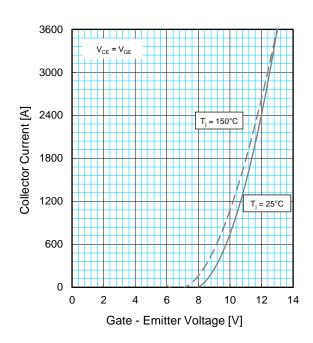
Note8. The maximum specified value is under the condition of using PCB mounted on the power module. In case no PCB is used this maximum torque

for M4 screw is 2.0 Nm.

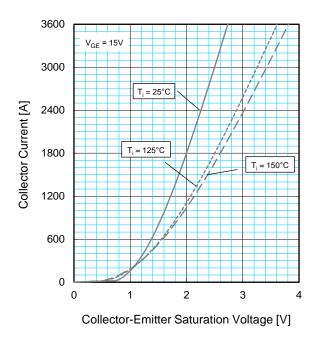
OUTPUT CHARACTERISTICS (TYPICAL)



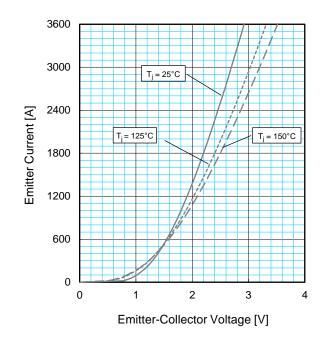
TRANSFER CHARACTERISTICS (TYPICAL)



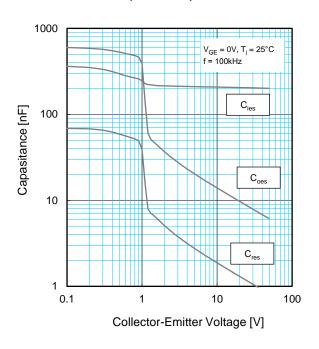
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



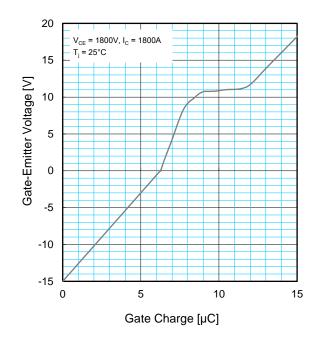
FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



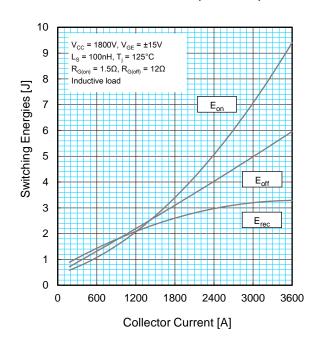
CAPACITANCE CHARACTERISTICS (TYPICAL)



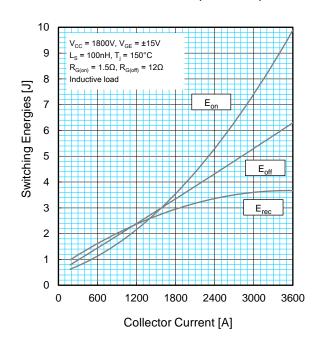
GATE CHARGE CHARACTERISTICS (TYPICAL)



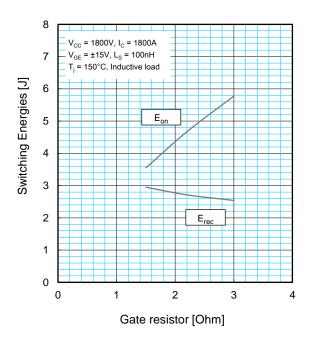
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



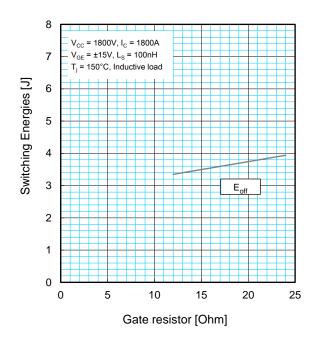
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



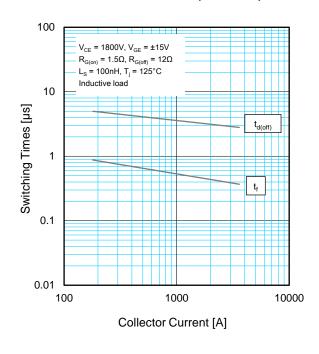
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



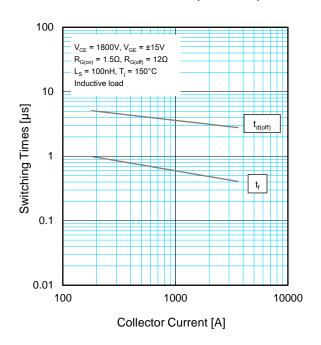
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



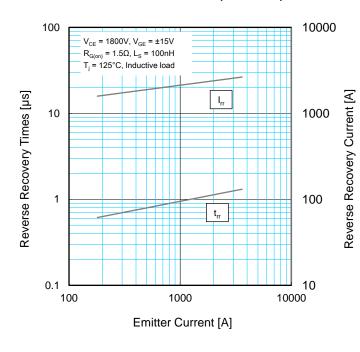
HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



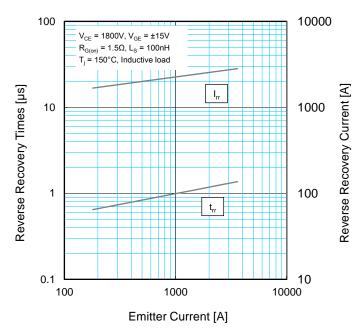
HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



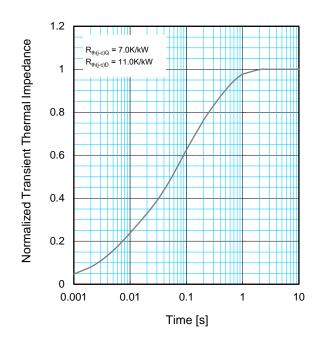
FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS



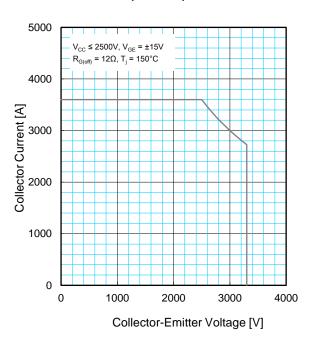
$$Z_{th(j-c)}(t) = \sum_{i=1}^{n} R_{i} \left\{ 1 - \exp^{\left(-\frac{t}{\tau_{i}}\right)} \right\}$$

	1	2	3	4
R _i / R _{th(j-c)} :	0.0096	0.1893	0.4044	0.3967
τ _i [sec]:	0.0001	0.0058	0.0602	0.3512

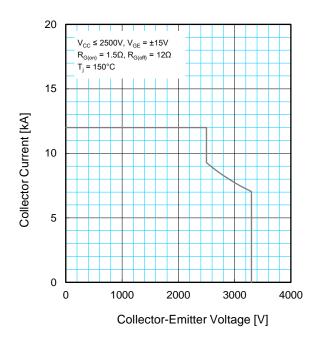
INSULATED TYPE

PERFORMANCE CURVES

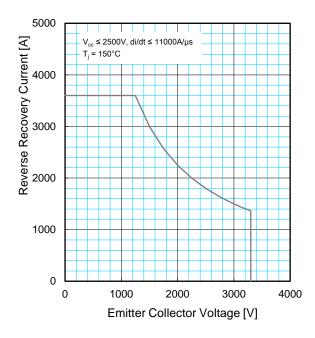
REVERSE BIAS SAFE OPERATING AREA (RBSOA)



SHORT CIRCUIT SAFE OPERATING AREA (SCSOA)



FREE-WHEEL DIODE REVERSE RECOVERY SAFE OPERATING AREA (RRSOA)



< High Voltage Insulated Gate Bipolar Transistor: HVIGBT >

CM1800HC-66X

HIGH POWER SWITCHING USE INSULATED TYPE

5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

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CM1800HC-66X

HIGH POWER SWITCHING USE

INSULATED TYPE

5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

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